| © Copy   | <b>tial Compositi</b><br>right 2005. IPC, B<br>ional and Pan-Am                              | annockbi   | urn, Illinois. A          | ll rights reserved untions. | under both              | This docume<br>level parts, t  | ent is a decla<br>he declaration | aration on enco           | of the sub<br>ompasses a | stances v<br>all lower | vithin the<br>level mat         | manufacture<br>erials for wh    | er listed it<br>nich the m | em. Not<br>anufact | te: if the<br>urer has | item is an ass<br>engineering re | embly with lowe<br>esponsibility. |
|--|--|------------|---------------------------|-----------------------------|-------------------------|--|----------------------------------|---------------------------|--------------------------|------------------------|---------------------------------|---------------------------------|----------------------------|--------------------|------------------------|----------------------------------|-----------------------------------|
|  | IPC Web Site for Information on IPC-1752 Standard Form<br>http://www.ipc.org/IPC-175x Distri |            |                           |                             | Form Type<br>Distribute | Type * Declaration Class *   bute Class 6 - RoHS Yes/No, Homogeneous Mai |                                  |                           |                          |                        | eous Materia                    | rials and Mfg Information       |                            |                    |                        |                                  |                                   |
| Supplier Information                           |  |            |                           |                             |                         |  |                                  |                           |                          |                        |                                 |                                 |                            |                    |                        |                                  |                                   |
| Company name*                                  |  |            | Company unique ID         |                             |                         | Unique ID Authority  |                                  |                           |                          |                        | Response Date*                  |                                 |                            |                    |                        |                                  |                                   |
| onsemi   |  |            |                           |                             |                         |  |                                  |                           |                          |                        |                                 |                                 | 2024-09-23                 |                    |                        |                                  |                                   |
| Contact Name                                   |  |            | Title - Contact           |                             |                         |  | Phone - Contact*                 |                           |                          |                        |                                 |                                 | Email - Contact*           |                    |                        |                                  |                                   |
| Product-Env-Stewards                           |  |            | Product Enviro Compliance |                             |                         | NA   |                                  |                           |                          |                        | Product-Env-Stewards@onsemi.com |                                 |                            |                    |                        |                                  |                                   |
| Authorized Representative*                     |  |            | Title - Representative    |                             |                         | Phone - Representative*  |                                  |                           |                          |                        | Email - Representative*         |                                 |                            |                    |                        |                                  |                                   |
| Product-Env-Stewards                           |  |            | Product Enviro Compliance |                             |                         |  | NA                               |                           |                          |                        |                                 | Product-Env-Stewards@onsemi.com |                            |                    |                        |                                  |                                   |
| Requester Item Nur                             | Requester Item Number Mfr Iter   |            | Number Mfr Item Name      |                             |                         | E  |                                  | Date V                    | Version                  | М                      | Manufacturing Site              |                                 | V                          | Veight*            | :                      | UOM                              | Unit Type                         |
|  | FDMC86   |            | 244                       | FET 150V 134.0 mOhm MLP33   |                         |  | 2024-09-23                       | 3                         |                          | PBB                    |                                 | 21.076                          |                            |                    | mg                     | Each                             |                                   |
| Manufacturing Proccess                         | 5 Information  |            |                           |                             |                         |  |                                  |                           |                          |                        |                                 |                                 |                            |                    |                        |                                  |                                   |
| Terminal Plating / Grid Array Material         |  | Те         | erminal Base Alloy J-S    |                             | J-STD-020 MS            | MSL Rating   |                                  | Peak Process Body Tempera |                          | nperature              | ture Max Time at Peak T         |                                 | Temperature Number         |                    | umber of               | mber of Reflow Cycles            |                                   |
| Precious metal (e.g. Ag,Au, NiPdAu) (no<br>Sn) |  | ) (no C    | CU Alloy 1                |                             | 1                       |  | 260                              |                           | (                        | С                      |                                 | <b>30</b> seco                  |                            | seconds 3          |                        |                                  |                                   |
| Comments                                       |  |            |                           |                             |                         |  |                                  |                           |                          |                        |                                 |                                 |                            |                    |                        |                                  |                                   |
| evel 1 - maximum time at pea                   | k temperature du   | uring sole | dering is 10-3            | 0 seconds                   |                         |  |                                  |                           |                          |                        |                                 |                                 |                            |                    |                        |                                  |                                   |
| For more information regardi                   | ng material comp   | position p | lease refer to            | page 3                      |                         |  |                                  |                           |                          |                        |                                 |                                 |                            |                    |                        |                                  |                                   |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  |  | nium (Cr6+), Polybro   | ominated Biphenyls (PBB), Polybron  | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth |   |  |  |  |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe  | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted  |   |  |  |  |  |  |  |  |  |  |
| Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.  |  |  |   |   |   |  |  |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital   | lly sign the declaration (if required by the  |  |  |  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS        | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------|--------|--------|-----------------|
| Die                  | 1.05   | mg              | Supplier | Silicon (Si)               | 7440-21-3  |        | 1.05   | mg              |
| Die Attach           | 0.198  | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.1584 | mg              |
|                      |        |                 | Supplier | Phenolic Resin-2           | 54208-63-8 |        | 0.0396 | mg              |
| Lead Frame           | 7.664  | mg              | Supplier | Zinc (Zn)                  | 7440-66-6  |        | 0.01   | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6  |        | 0.184  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 7.47   | mg              |
| Mold Compound-Black  | 11.505 | mg              | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 |        | 2.19   | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4  |        | 0.115  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0 |        | 9.2    | mg              |
| Plating              | 0.198  | mg              | Supplier | Palladium (Pd)             | 7440-05-3  |        | 0.018  | mg              |
|                      |        |                 | В        | Nickel (Ni)                | 7440-02-0  |        | 0.178  | mg              |
|                      |        |                 | Supplier | Gold (Au)                  | 7440-57-5  |        | 0.002  | mg              |
| Wire Bond - Cu       | 0.461  | mg              | Supplier | Copper (Cu)                | 7440-50-8  |        | 0.461  | mg              |